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Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



|                    |      |
|--------------------|------|
| $V_{DSS}$          | -20V |
| $R_{DS(on)}(Max.)$ | 26mΩ |
| $I_D$              | ±10A |
| $P_D$              | 2W   |

### ●Features

- 1) Low on - resistance.
- 2) High Power small mold Package (HUML2020L8).
- 3) Pb-free lead plating ; RoHS compliant.
- 4) Halogen Free.

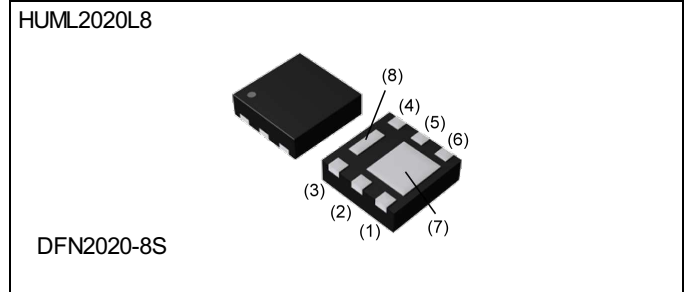
### ●Application

Switching  
Load switch

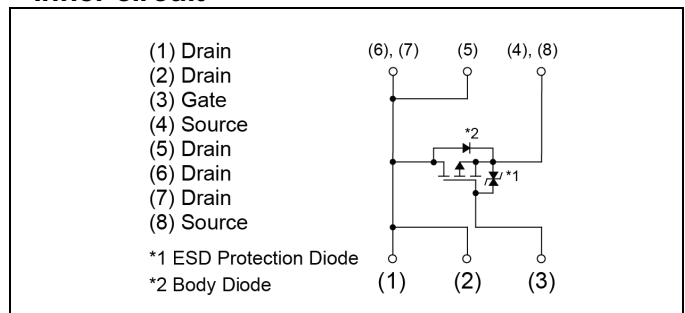
### ●Absolute maximum ratings ( $T_a = 25^{\circ}C$ )

| Parameter                    | Symbol             | Value       | Unit |
|------------------------------|--------------------|-------------|------|
| Drain - Source voltage       | $V_{DSS}$          | -20         | V    |
| Continuous drain current     | $I_D$              | ±10         | A    |
| Pulsed drain current         | $I_{D,pulse}^{*1}$ | ±20         | A    |
| Gate - Source voltage        | $V_{GSS}$          | 0~-8        | V    |
| Power dissipation            | $P_D^{*2}$         | 2           | W    |
| Junction temperature         | $T_j$              | 150         | °C   |
| Range of storage temperature | $T_{stg}$          | -55 to +150 | °C   |

### ●Outline



### ●Inner circuit



### ●Packaging specifications

| Type                      | Packing        | Embossed Tape |
|---------------------------|----------------|---------------|
|                           | Reel size (mm) | 180           |
| Tape width (mm)           | 8              |               |
| Basic ordering unit (pcs) | 3000           |               |
| Taping code               | TR             |               |
| Marking                   | SJ             |               |

## ● Thermal resistance

| Parameter                              | Symbol          | Values |      |      | Unit |
|--|-----------------|--------|------|------|------|
|  |                 | Min.   | Typ. | Max. |      |
| Thermal resistance, junction - ambient | $R_{thJA}^{*2}$ | -      | 62.5 | -    | °C/W |

● Electrical characteristics ( $T_a = 25^\circ\text{C}$ )

| Parameter                                      | Symbol                                  | Conditions                                       | Values |      |      | Unit          |
|--|---|--|--------|------|------|---------------|
|  |   |  | Min.   | Typ. | Max. |               |
| Drain - Source breakdown voltage               | $V_{(BR)DSS}$                           | $V_{GS} = 0V, I_D = -1mA$                        | -20    | -    | -    | V             |
| Breakdown voltage temperature coefficient      | $\frac{\Delta V_{(BR)DSS}}{\Delta T_j}$ | $I_D = -1mA$<br>referenced to $25^\circ\text{C}$ | -      | -9.3 | -    | mV/°C         |
| Zero gate voltage drain current                | $I_{DSS}$                               | $V_{DS} = -20V, V_{GS} = 0V$                     | -      | -    | -10  | $\mu\text{A}$ |
| Gate - Source leakage current                  | $I_{GSS}$                               | $V_{GS} = -8V, V_{DS} = 0V$                      | -      | -    | -10  | $\mu\text{A}$ |
| Gate threshold voltage                         | $V_{GS(th)}$                            | $V_{DS} = -10V, I_D = -1mA$                      | -0.3   | -    | -1.0 | V             |
| Gate threshold voltage temperature coefficient | $\frac{\Delta V_{GS(th)}}{\Delta T_j}$  | $I_D = -1mA$<br>referenced to $25^\circ\text{C}$ | -      | 1.8  | -    | mV/°C         |
| Static drain - source on - state resistance    | $R_{DS(on)}^{*3}$                       | $V_{GS} = -4.5V, I_D = -5.0A$                    | -      | 18   | 26   | mΩ            |
|  |   | $V_{GS} = -2.5V, I_D = -2.5A$                    | -      | 22   | 31   |               |
|  |   | $V_{GS} = -1.8V, I_D = -2.5A$                    | -      | 27   | 45   |               |
|  |   | $V_{GS} = -1.5V, I_D = -1.0A$                    | -      | 32   | 65   |               |
| Forward Transfer Admittance                    | $ Y_{fs} ^{*3}$                         | $V_{DS} = -10V, I_D = -5.0A$                     | 8      | -    | -    | S             |

\*1  $P_w \leq 10\mu\text{s}$ , Duty cycle  $\leq 1\%$ 

\*2 MOUNTED ON 40mm×40mm Cu BOARD

\*3 Pulsed

**●Electrical characteristics ( $T_a = 25^\circ\text{C}$ )**

| Parameter                    | Symbol            | Conditions                            | Values |      |      | Unit |
|------------------------------|-------------------|---------------------------------------|--------|------|------|------|
|                              |                   |                                       | Min.   | Typ. | Max. |      |
| Input capacitance            | $C_{iss}$         | $V_{GS} = 0V$                         | -      | 5500 | -    | pF   |
| Output capacitance           | $C_{oss}$         | $V_{DS} = -10V$                       | -      | 230  | -    |      |
| Reverse transfer capacitance | $C_{rss}$         | $f = 1\text{MHz}$                     | -      | 210  | -    |      |
| Turn - on delay time         | $t_{d(on)}^{*3}$  | $V_{DD} \approx -10V, V_{GS} = -4.5V$ | -      | 16   | -    | ns   |
| Rise time                    | $t_r^{*3}$        | $I_D = -2.5A$                         | -      | 16   | -    |      |
| Turn - off delay time        | $t_{d(off)}^{*3}$ | $R_L \approx 4.02\Omega$              | -      | 580  | -    |      |
| Fall time                    | $t_f^{*3}$        | $R_G = 10\Omega$                      | -      | 160  | -    |      |

**●Gate charge characteristics ( $T_a = 25^\circ\text{C}$ )**

| Parameter            | Symbol        | Conditions             | Values |      |      | Unit |
|----------------------|---------------|------------------------|--------|------|------|------|
|                      |               |                        | Min.   | Typ. | Max. |      |
| Total gate charge    | $Q_g^{*3}$    | $V_{DD} \approx -10V,$ | -      | 55   | -    | nC   |
| Gate - Source charge | $Q_{gs}^{*3}$ | $I_D = -5.0A,$         | -      | 6.4  | -    |      |
| Gate - Drain charge  | $Q_{gd}^{*3}$ | $V_{GS} = -4.5V$       | -      | 8.4  | -    |      |

**●Body diode electrical characteristics (Source-Drain) ( $T_a = 25^\circ\text{C}$ )**

| Parameter                             | Symbol        | Conditions                 | Values |      |      | Unit |
|---------------------------------------|---------------|----------------------------|--------|------|------|------|
|                                       |               |                            | Min.   | Typ. | Max. |      |
| Body diode continuous forward current | $I_S$         | $T_a = 25^\circ\text{C}$   | -      | -    | -1.6 | A    |
| Body diode pulse current              | $I_{SP}^{*1}$ |                            | -      | -    | -20  | A    |
| Forward voltage                       | $V_{SD}^{*3}$ | $V_{GS} = 0V, I_S = -1.6A$ | -      | -    | -1.2 | V    |

● Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

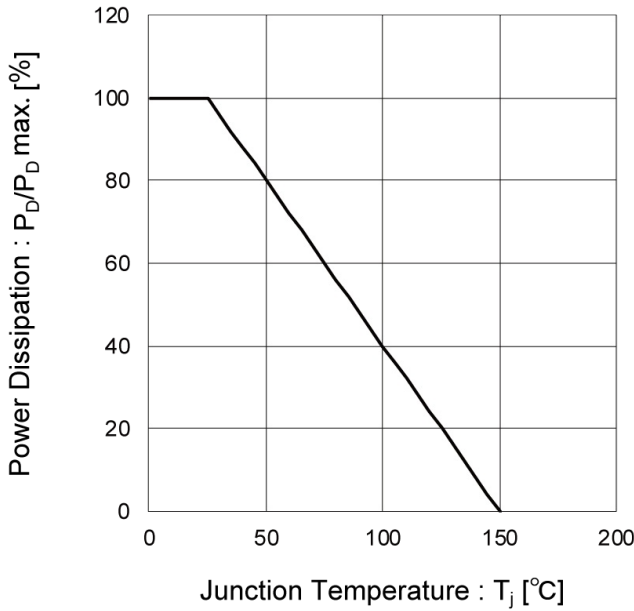


Fig.2 Maximum Safe Operating Area

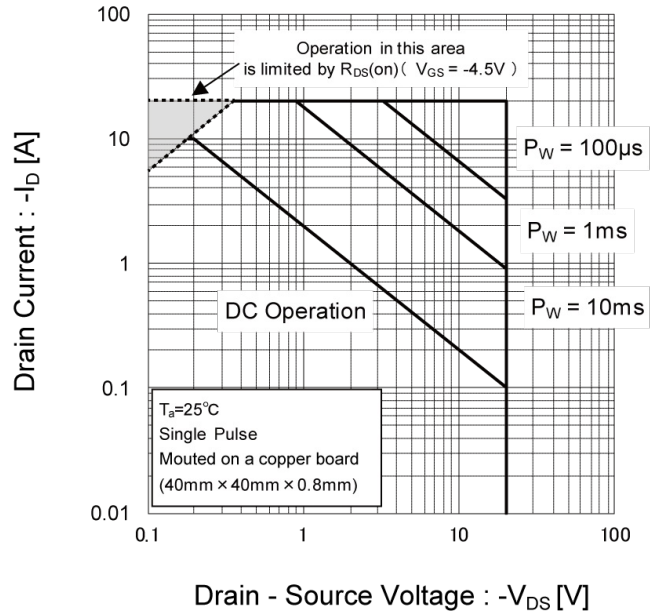


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

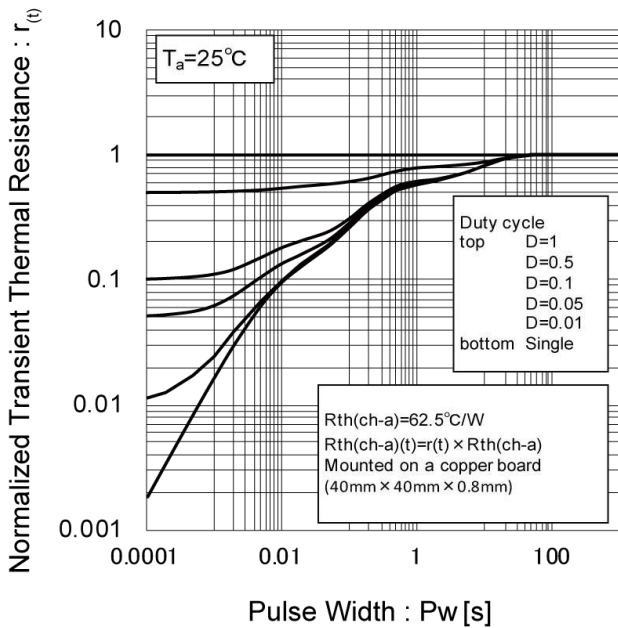
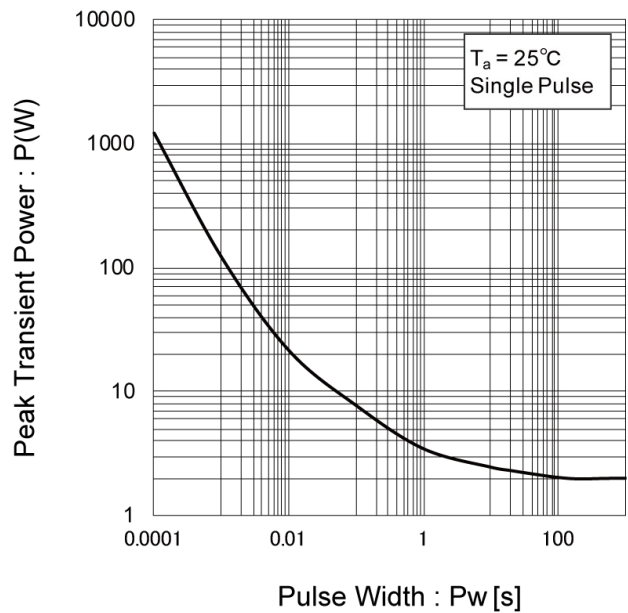


Fig.4 Single Pulse Maximum Power dissipation



● Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)

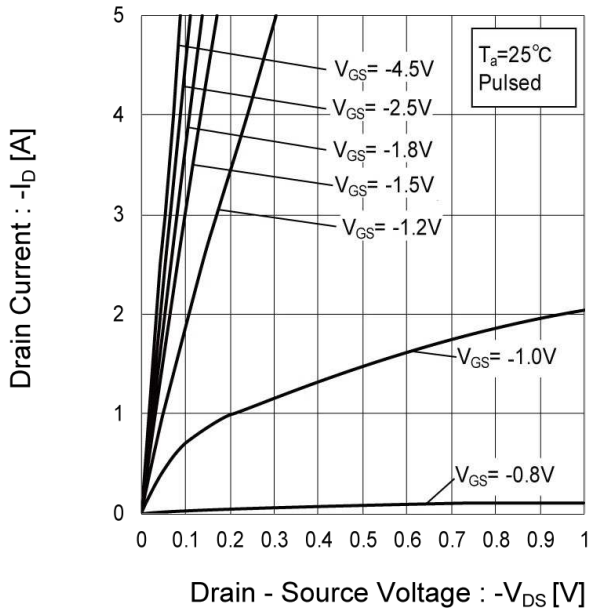


Fig.6 Typical Output Characteristics(II)

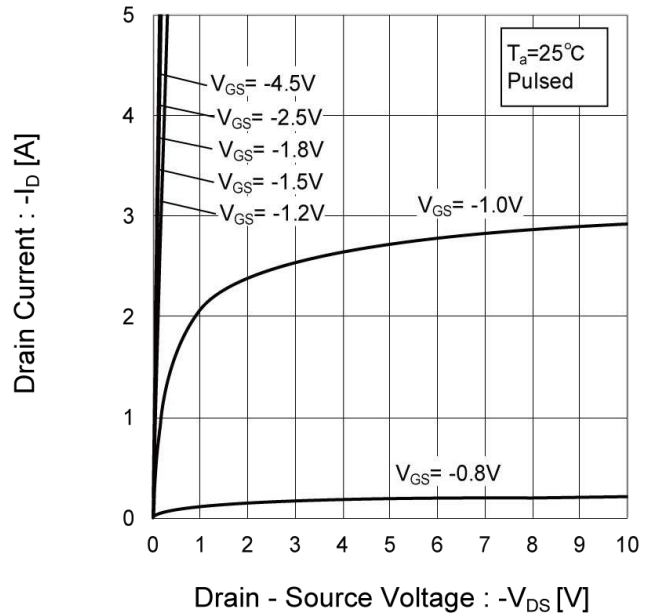


Fig.7 Breakdown Voltage vs. Junction Temperature

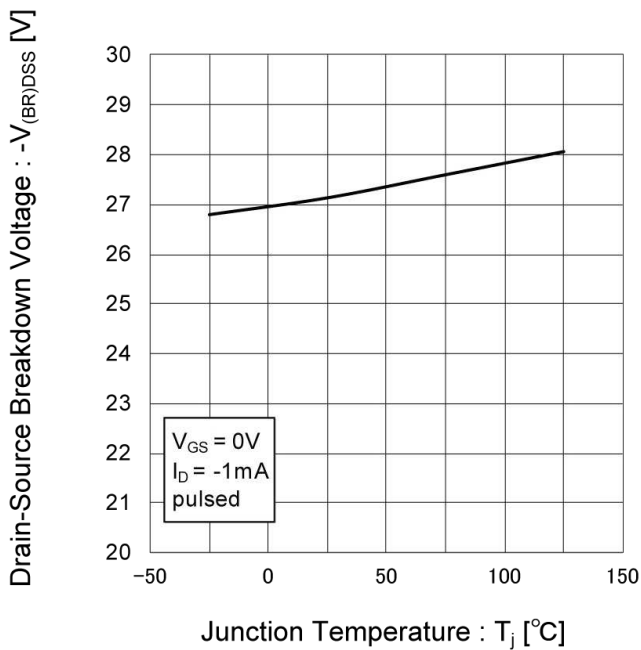
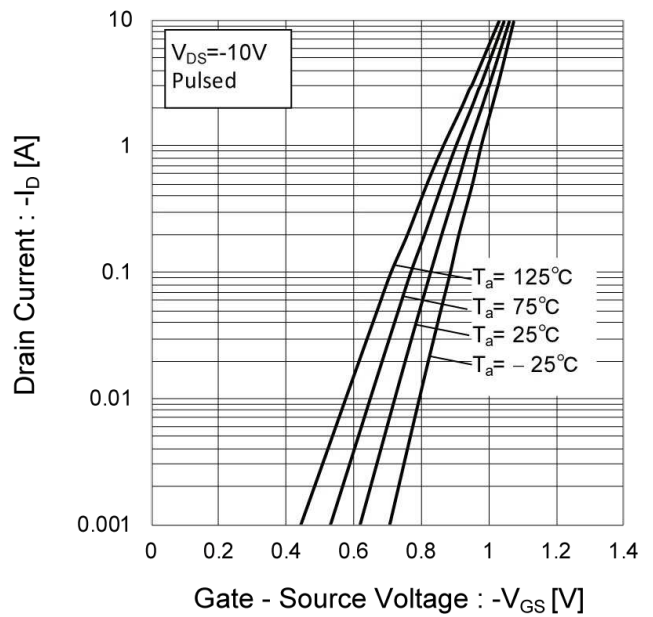


Fig.8 Typical Transfer Characteristics



●Electrical characteristic curves

Fig.9 Gate Threshold Voltage vs. Junction Temperature

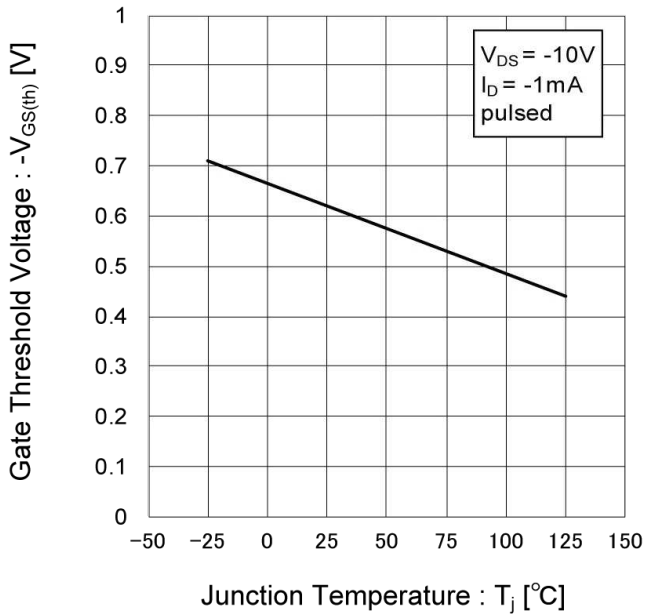


Fig.10 Transconductance vs. Drain Current

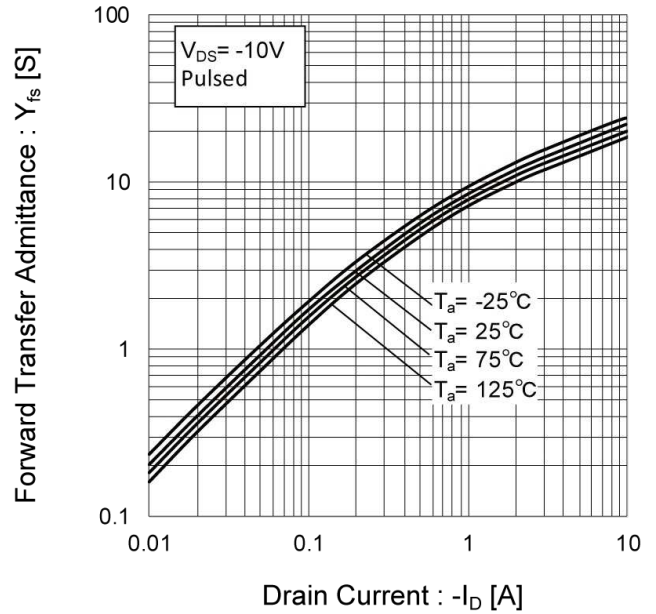


Fig.11 Drain Current Derating Curve

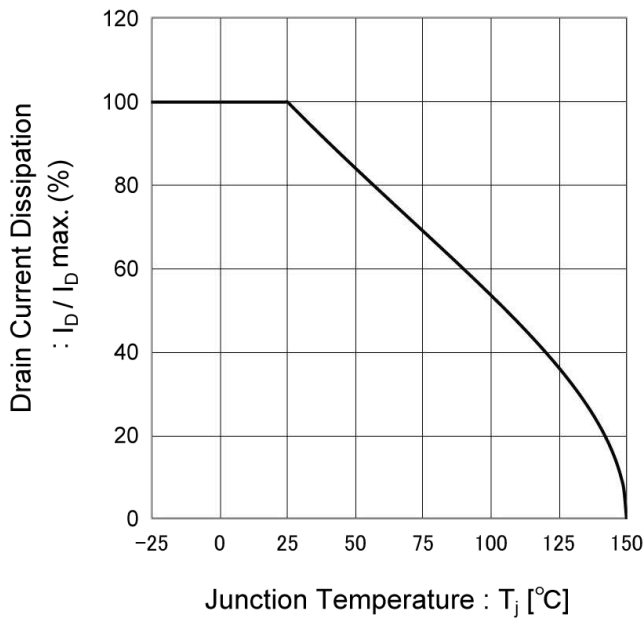
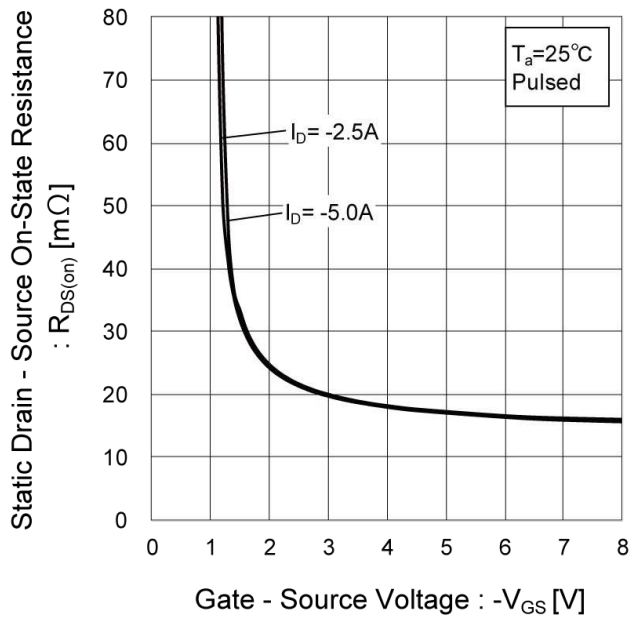


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage



● Electrical characteristic curves

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

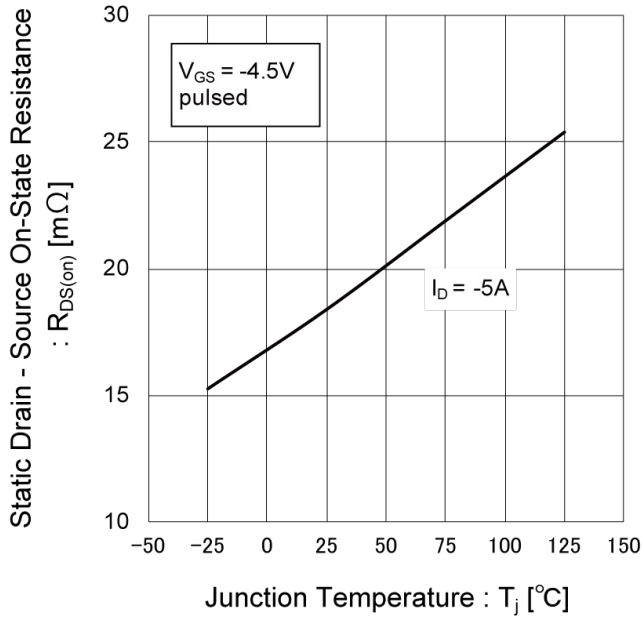


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current(I)

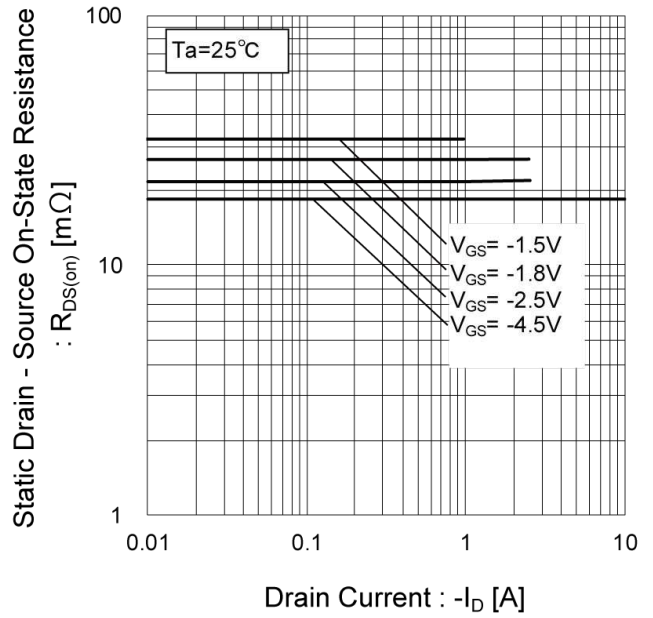


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)

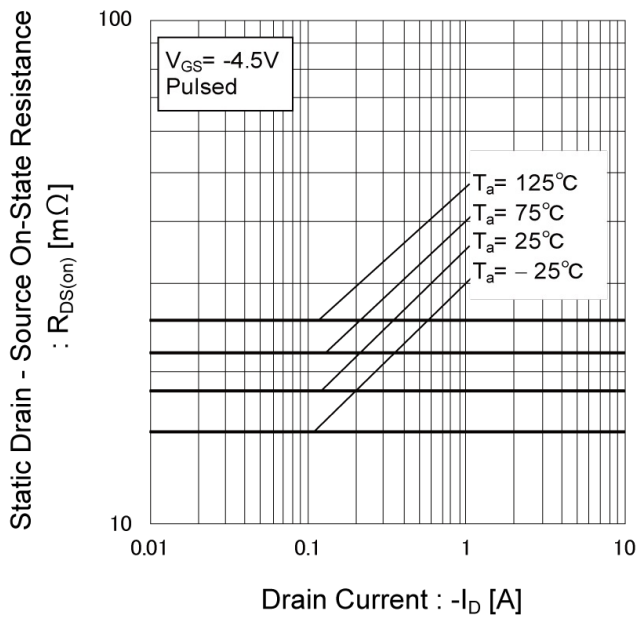
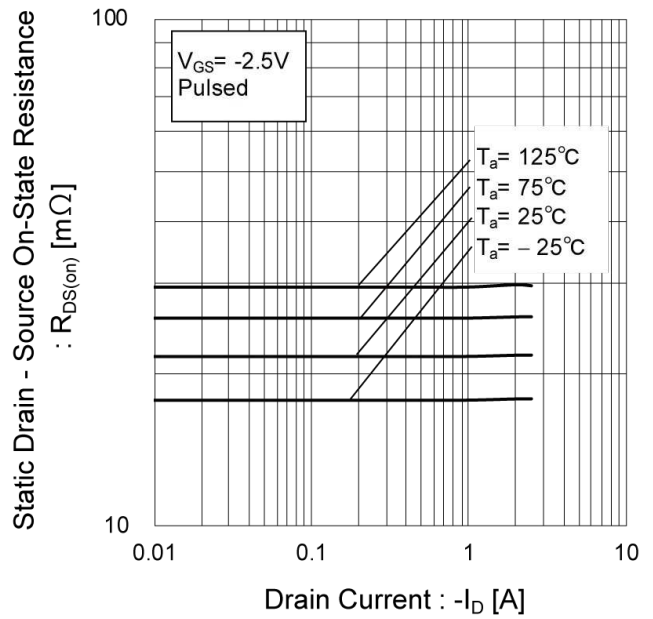


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current(III)



● Electrical characteristic curves

Fig.17 Static Drain - Source On - State Resistance vs. Drain Current(IV)

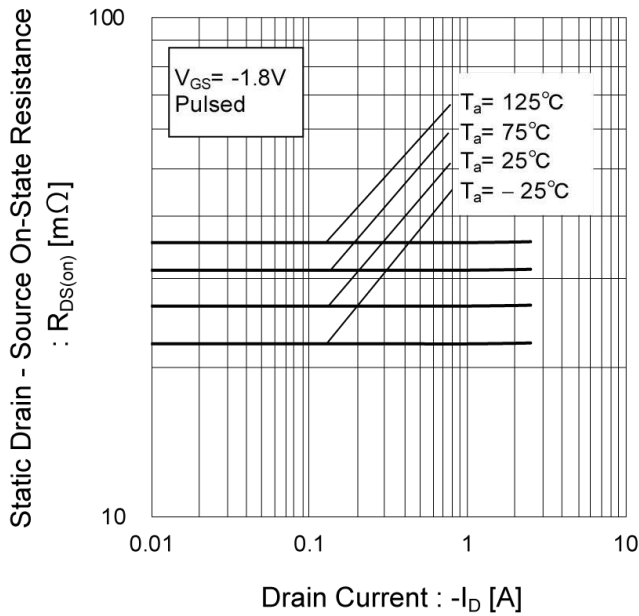


Fig.18 Static Drain - Source On - State Resistance vs. Drain Current(V)

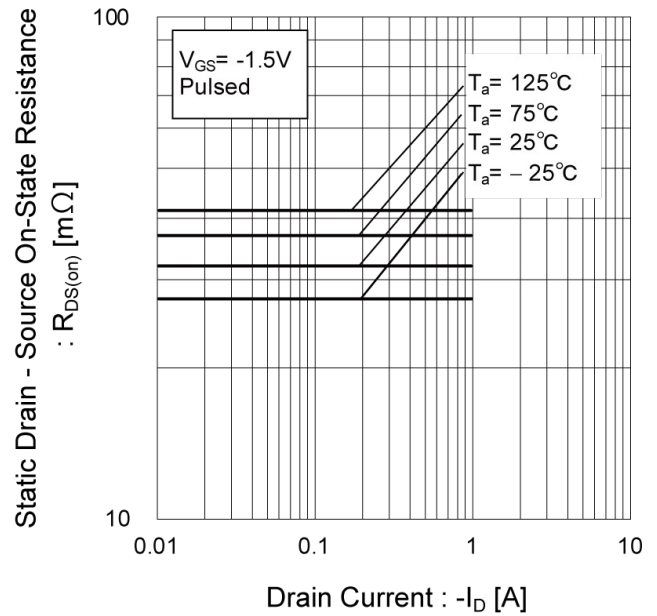


Fig.19 Typical Capacitance vs. Drain - Source Voltage

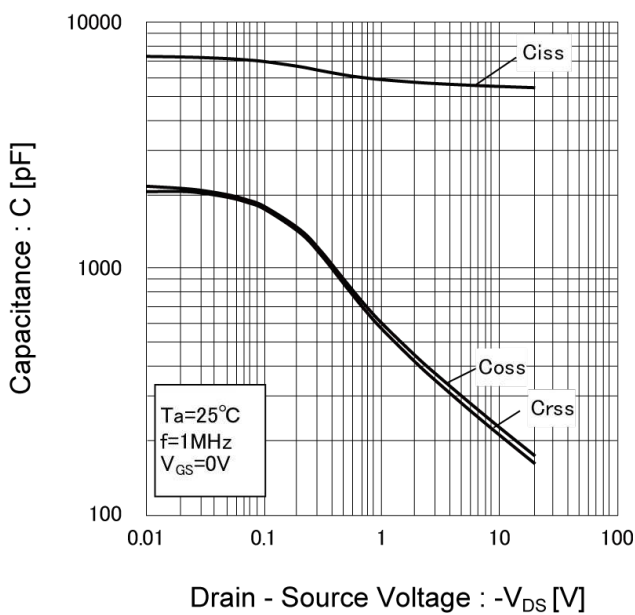
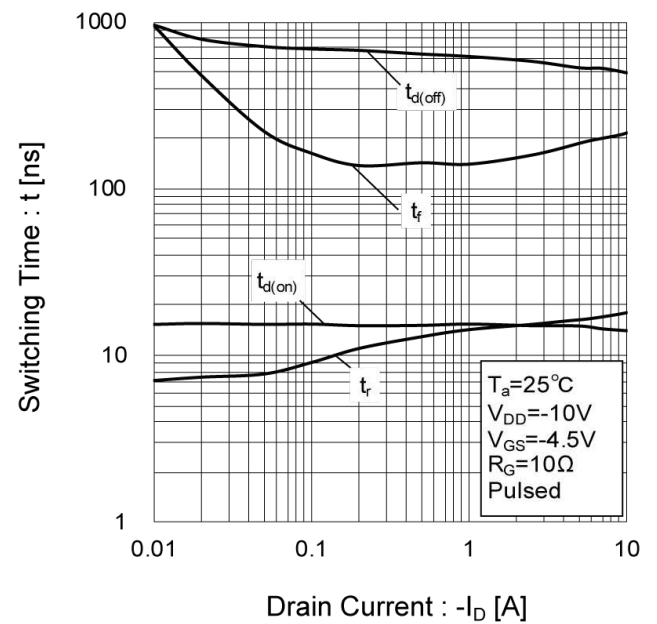


Fig.20 Switching Characteristics



● Electrical characteristic curves

Fig.21 Dynamic Input Characteristics

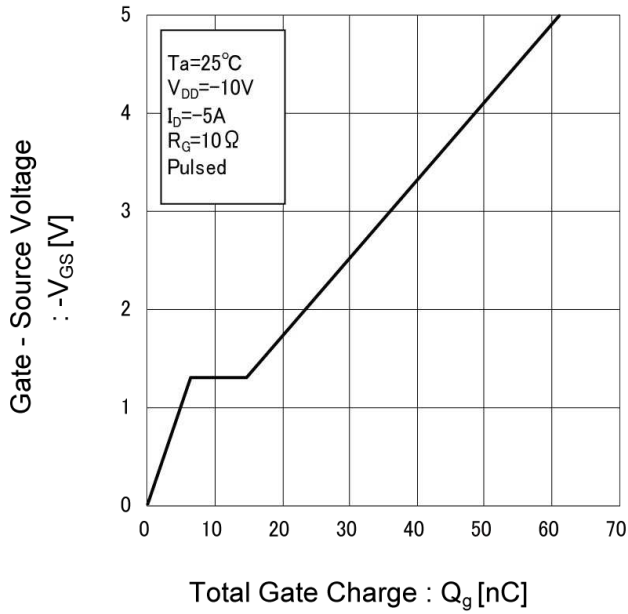
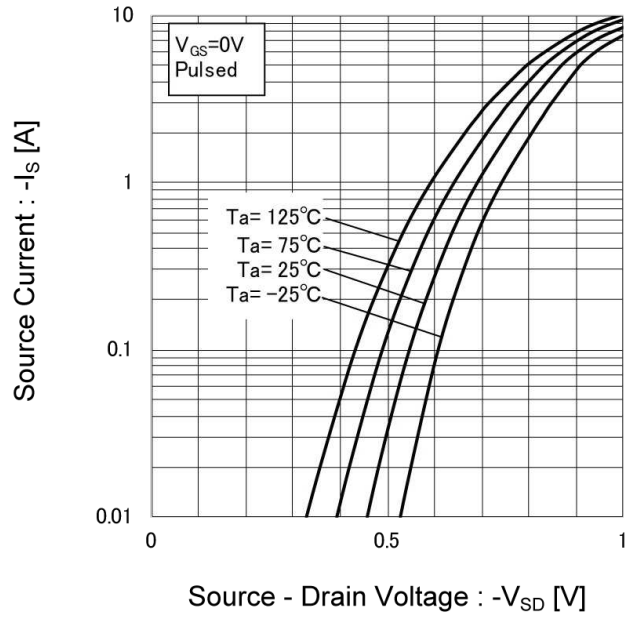


Fig.22 Source Current vs. Source Drain Voltage



● Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

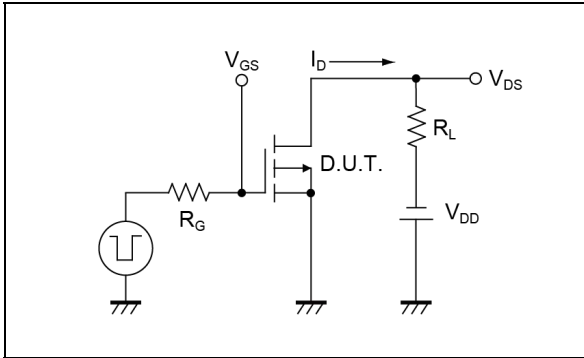


Fig.1-2 Switching Waveforms

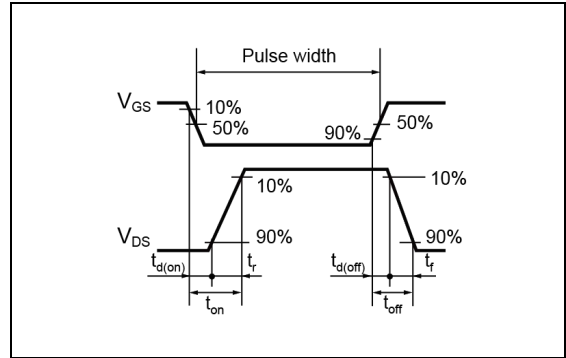


Fig.2-1 Gate Charge Measurement Circuit

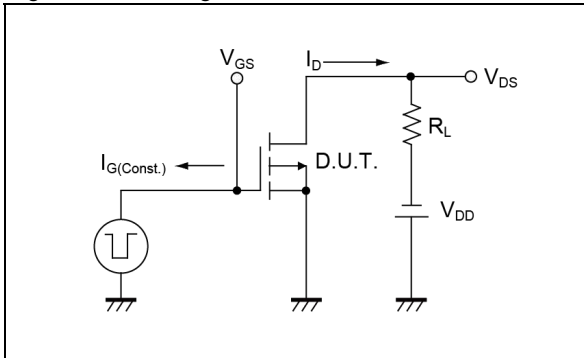
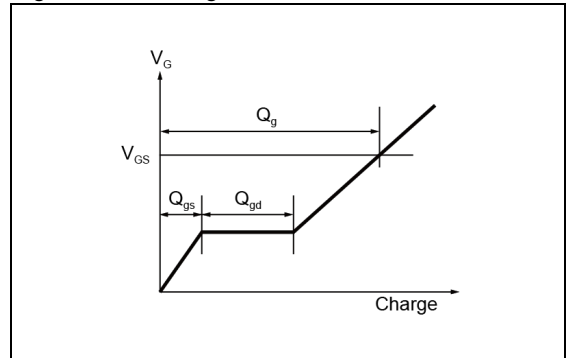


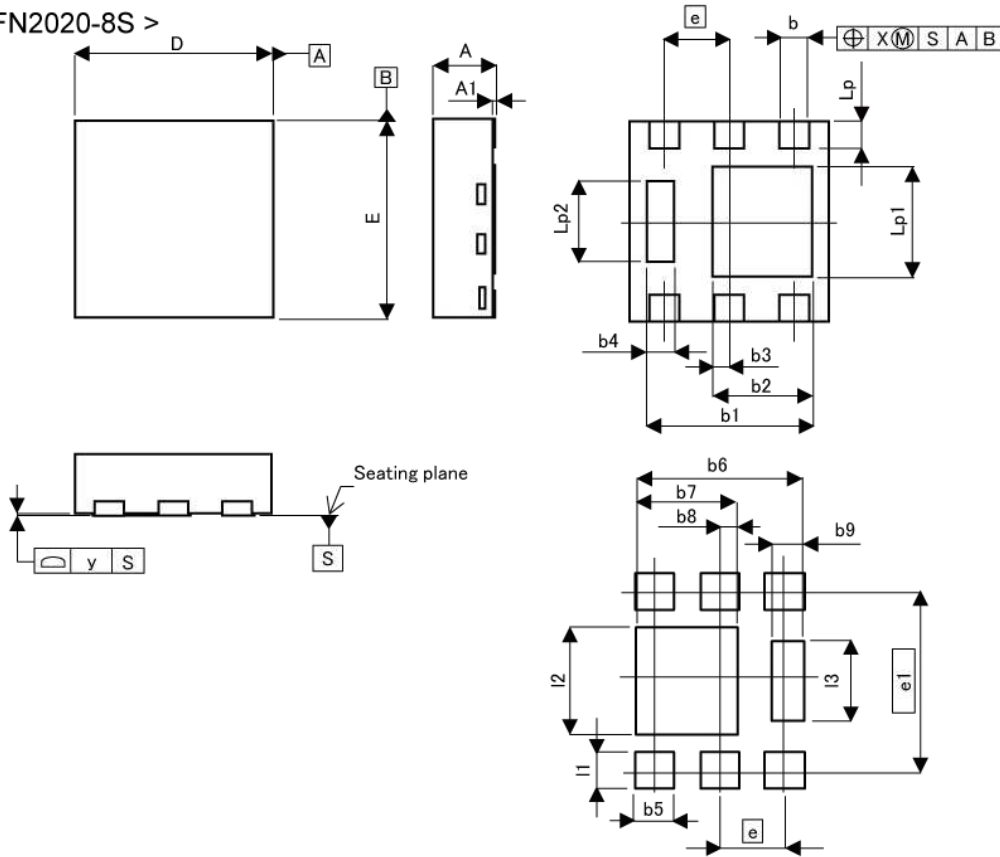
Fig.2-2 Gate Charge Waveform



●Dimensions

HUML2020L8 (Single)

< DFN2020-8S >



Pattern of terminal position areas  
[Not a pattern of soldering pads]

| DIM | MILIMETERS |       | INCHES |       |
|-----|------------|-------|--------|-------|
|     | MIN        | MAX   | MIN    | MAX   |
| A   | 0.55       | 0.65  | 0.022  | 0.026 |
| A1  | 0.00       | 0.05  | 0.000  | 0.002 |
| b   | 0.25       | 0.35  | 0.010  | 0.014 |
| b1  | 1.55       | 1.75  | 0.061  | 0.069 |
| b2  | 0.95       | 1.05  | 0.037  | 0.041 |
| b3  | 0.175      |       | 0.007  |       |
| b4  | 0.20       | 0.30  | 0.008  | 0.012 |
| D   | 1.90       | 2.10  | 0.075  | 0.083 |
| E   | 1.90       | 2.10  | 0.075  | 0.083 |
| e   | 0.65       |       | 0.026  |       |
| Lp  | 0.225      | 0.325 | 0.009  | 0.013 |
| Lp1 | 1.05       | 1.15  | 0.041  | 0.045 |
| Lp2 | 0.75       | 0.85  | 0.030  | 0.033 |
| x   | -          | 0.10  | -      | 0.004 |
| y   | -          | 0.10  | -      | 0.004 |

| DIM | MILIMETERS |       | INCHES |       |
|-----|------------|-------|--------|-------|
|     | MIN        | MAX   | MIN    | MAX   |
| b5  | -          | 0.45  | -      | 0.018 |
| b6  | -          | 1.75  | -      | 0.069 |
| b7  | -          | 1.05  | -      | 0.041 |
| b8  | 0.175      |       | 0.007  |       |
| b9  | -          | 0.30  | -      | 0.012 |
| e1  | 1.725      |       | 0.068  |       |
| l1  | -          | 0.425 | -      | 0.017 |
| l2  | -          | 1.15  | -      | 0.045 |
| l3  | -          | 0.85  | -      | 0.033 |

Dimension in mm/inches

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